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Product Change Notification - CYER-09HJXI365 [\(Printer Friendly\)](#)

Date: 06 Feb 2014

Notification subject: CCB 1155.05 Final Notification: Qualification of selected products available in the 28L SPDIP, 18L PDIP, and 8L PDIP packages with palladium coated copper (PdCu) bond wire at MTAI assembly site.

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:
See attachments of affected catalog part numbers (CPN) labeled as...
PCN_CYER-09HJXI365_Affected_CPN.xls
PCN_CYER-09HJXI365_Affected_CPN.pdf

Description of Change:
Qualification of selected products available in the 28L SPDIP, 8L PDIP, and 18L PDIP packages with palladium coated copper (PdCu) bond wire at MTAI assembly site.

NOTE: Selected products are non-automotive standalone analog and PIC MCU devices. Please review the affected CPN lists (attached) to identify the actual parts affected.

Pre Change:
Gold (Au) wire

Post Change:
Palladium coated copper (PdCu) bond wire

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability

Change Implementation Status:
In progress

Estimated First Ship Dates:
Devices Previously Identified: October 18, 2013 (Date code: 1342)
Devices added 12/18/2013: January 17, 2014 (Date code: 1403)
Devices added 2/6/2014: February 28/2014 (Date code: 1409)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
August 23, 2013: Initial notification issue date.
September 17, 2013: Final notification issue date. Attached qualification report.
December 18, 2013: Revised PCN to include various devices that will be affected by this change. Revised the attached parts affects list so show which devices were added and the estimated first ship date for all devices. Added the new estimated first ship date of 1/17/2014 for the newly added devices.
February 6, 2014: Revised PCN to include various devices that will be affected by this change. Revised the attached parts affects list so show which devices were added and the estimated first ship date for all devices. Added the new estimated first ship date of 2/28/2014 for the newly added devices.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_CYER-09HJXI365_Affected CPNr.pdf](#)
[PCN_CYER-09HJXI365_Qual Report.pdf](#)
[PCN_CYER-09HJXI365_Affected CPNr.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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